

MC14040B

12-Bit Binary Counter

The MC14040B 12-stage binary counter is constructed with MOS P-Channel and N-Channel enhancement mode devices in a single monolithic structure. This part is designed with an input wave shaping circuit and 12 stages of ripple-carry binary counter. The device advances the count on the negative-going edge of the clock pulse. Applications include time delay circuits, counter controls, and frequency-driving circuits.

Features

- Fully Static Operation
- Diode Protection on All Inputs
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Capable of Driving Two Low-power TTL Loads or One Low-power Schottky TTL Load Over the Rated Temperature Range
- Common Reset Line
- Pin-for-Pin Replacement for CD4040B
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS (Voltages Referenced to V_{SS})

Symbol	Parameter	Value	Unit
V _{DD}	DC Supply Voltage Range	-0.5 to +18.0	V
V _{in} , V _{out}	Input or Output Voltage Range (DC or Transient)	-0.5 to V _{DD} + 0.5	V
I _{in} , I _{out}	Input or Output Current (DC or Transient) per Pin	±10	mA
P _D	Power Dissipation, per Package (Note 1)	500	mW
T _A	Ambient Temperature Range	-55 to +125	°C
T _{stg}	Storage Temperature Range	-65 to +150	°C
T _L	Lead Temperature (8-Second Soldering)	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Temperature Derating:

Plastic "P and D/DW" Packages: - 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range V_{SS} ≤ (V_{in} or V_{out}) ≤ V_{DD}.

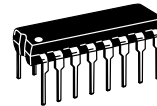
Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.



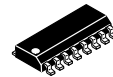
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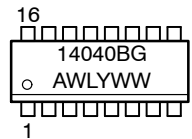
MARKING DIAGRAMS



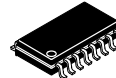
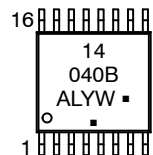
PDIP-16
P SUFFIX
CASE 648



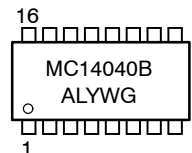
SOIC-16
D SUFFIX
CASE 751B



TSSOP-16
DT SUFFIX
CASE 948F



SOEIAJ-16
F SUFFIX
CASE 966



A = Assembly Location
WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week
G or ■ = Pb-Free Package

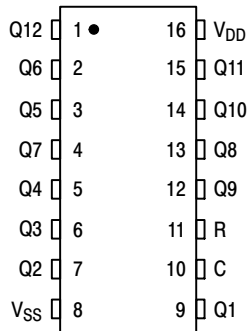
(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

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PIN ASSIGNMENT

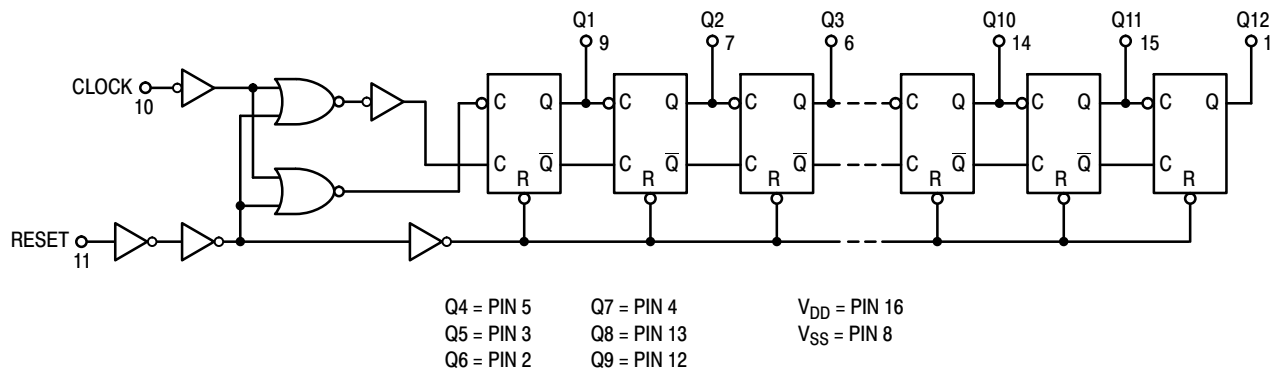


TRUTH TABLE

Clock	Reset	Output State
	0	No Change
	0	Advance to next state
X	1	All Outputs are low

X = Don't Care

LOGIC DIAGRAM



ORDERING INFORMATION

Device	Package	Shipping [†]
MC14040BCPG	PDIP-16 (Pb-Free)	500 Units / Tape & Ammunition Box
MC14040BDG	SOIC-16 (Pb-Free)	48 Units / Rail
MC14040BDR2G	SOIC-16 (Pb-Free)	2500 Units / Tape & Reel
MC14040BDTR2G	TSSOP-16*	2500 Units / Tape & Reel
MC14040BFELG	SOEIAJ-16 (Pb-Free)	2000 Units / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*This package is inherently Pb-Free.

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ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

Characteristic	Symbol	V_{DD} Vdc	- 55°C		25°C			125°C		Unit
			Min	Max	Min	Typ (Note 2)	Max	Min	Max	
Output Voltage $V_{in} = V_{DD}$ or 0 $V_{in} = 0$ or V_{DD}	"0" Level V_{OL}	5.0	-	0.05	-	0	0.05	-	0.05	Vdc
		10	-	0.05	-	0	0.05	-	0.05	
		15	-	0.05	-	0	0.05	-	0.05	
	"1" Level V_{OH}	5.0	4.95	—	4.95	5.0	-	4.95	-	Vdc
		10	9.95	—	9.95	10	-	9.95	-	
		15	14.95	—	14.95	15	-	14.95	-	
Input Voltage "0" Level ($V_O = 4.5$ or 0.5 Vdc) ($V_O = 9.0$ or 1.0 Vdc) ($V_O = 13.5$ or 1.5 Vdc) "1" Level ($V_O = 0.5$ or 4.5 Vdc) ($V_O = 1.0$ or 9.0 Vdc) ($V_O = 1.5$ or 13.5 Vdc)	V_{IL}	5.0	-	1.5	-	2.25	1.5	-	1.5	Vdc
		10	-	3.0	-	4.50	3.0	-	3.0	
		15	-	4.0	-	6.75	4.0	-	4.0	
	V_{IH}	5.0	3.5	-	3.5	2.75	-	3.5	-	Vdc
		10	7.0	-	7.0	5.50	-	7.0	-	
		15	11	-	11	8.25	-	11	-	
Output Drive Current ($V_{OH} = 2.5$ Vdc) ($V_{OH} = 4.6$ Vdc) ($V_{OH} = 9.5$ Vdc) ($V_{OH} = 13.5$ Vdc) ($V_{OL} = 0.4$ Vdc) ($V_{OL} = 0.5$ Vdc) ($V_{OL} = 1.5$ Vdc)	Source I_{OH}	5.0	-3.0	-	-2.4	-4.2	-	-1.7	-	mAdc
		5.0	-0.64	-	-0.51	-0.88	-	-0.36	-	
		10	-1.6	-	-1.3	-2.25	-	-0.9	-	
		15	-4.2	-	-3.4	-8.8	-	-2.4	-	
	Sink I_{OL}	5.0	0.64	-	0.51	0.88	-	0.36	-	mAdc
		10	1.6	-	1.3	2.25	-	0.9	-	
15		4.2	-	3.4	8.8	-	2.4	-		
Input Current	I_{in}	15	-	± 0.1	-	± 0.00001	± 0.1	-	± 1.0	μ Adc
Input Capacitance ($V_{in} = 0$)	C_{in}	-	-	-	-	5.0	7.5	-	-	pF
Quiescent Current (Per Package)	I_{DD}	5.0	-	5.0	-	0.005	5.0	-	150	μ Adc
		10	-	10	-	0.010	10	-	300	
		15	-	20	-	0.015	20	-	600	
Total Supply Current (Notes 3 & 4) (Dynamic plus Quiescent, Per Package) ($C_L = 50$ pF on all outputs, all buffers switching)	I_T	5.0	$I_T = (0.42 \mu\text{A/kHz}) f + I_{DD}$							μ Adc
		10	$I_T = (0.85 \mu\text{A/kHz}) f + I_{DD}$							
		15	$I_T = (1.43 \mu\text{A/kHz}) f + I_{DD}$							

2. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

3. The formulas given are for the typical characteristics only at 25°C.

4. To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) Vfk$$

where: I_T is in μA (per package), C_L in pF, $V = (V_{DD} - V_{SS})$ in volts, f in kHz is input frequency, and $k = 0.001$.

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SWITCHING CHARACTERISTICS (Note 5) ($C_L = 50 \text{ pF}$, $T_A = 25^\circ\text{C}$)

Characteristic	Symbol	V_{DD} Vdc	Min	Typ (Note 6)	Max	Unit
Output Rise and Fall Time T_{TLH} , $T_{THL} = (1.5 \text{ ns/pF}) C_L + 25 \text{ ns}$ T_{TLH} , $T_{THL} = (0.75 \text{ ns/pF}) C_L + 12.5 \text{ ns}$ T_{TLH} , $T_{THL} = (0.55 \text{ ns/pF}) C_L + 9.5 \text{ ns}$	t_{TLH} , t_{THL}	5.0 10 15	- - -	100 50 40	200 100 80	ns
Propagation Delay Time Clock to Q1 t_{PHL} , $t_{PLH} = (1.7 \text{ ns/pF}) C_L + 315 \text{ ns}$ t_{PHL} , $t_{PLH} = (0.66 \text{ ns/pF}) C_L + 137 \text{ ns}$ t_{PHL} , $t_{PLH} = (0.5 \text{ ns/pF}) C_L + 95 \text{ ns}$	t_{PLH} , t_{PHL}	5.0 10 15	- - -	260 115 80	520 230 160	ns
Clock to Q12 t_{PHL} , $t_{PLH} = (1.7 \text{ ns/pF}) C_L + 2415 \text{ ns}$ t_{PHL} , $t_{PLH} = (0.66 \text{ ns/pF}) C_L + 867 \text{ ns}$ t_{PHL} , $t_{PLH} = (0.5 \text{ ns/pF}) C_L + 475 \text{ ns}$		5.0 10 15	- - -	1625 720 500	3250 1440 1000	ns
Propagation Delay Time Reset to Q_n $t_{PHL} = (1.7 \text{ ns/pF}) C_L + 485 \text{ ns}$ $t_{PHL} = (0.86 \text{ ns/pF}) C_L + 182 \text{ ns}$ $t_{PHL} = (0.5 \text{ ns/pF}) C_L + 145 \text{ ns}$	t_{PHL}	5.0 10 15	- - -	370 155 115	740 310 230	ns
Clock Pulse Width	t_{WH}	5.0 10 15	385 150 115	140 55 38	- - -	ns
Clock Pulse Frequency	f_{cl}	5.0 10 15	- - -	2.1 7.0 10.0	1.5 3.5 4.5	MHz
Clock Rise and Fall Time	t_{TLH} , t_{THL}	5.0 10 15	No Limit			ns
Reset Pulse Width	t_{WH}	5.0 10 15	960 360 270	320 120 80	- - -	ns
Reset Removal Time	t_{rem}	5.0 10 15	130 50 30	65 25 15	- - -	ns

5. The formulas given are for the typical characteristics only at 25°C.

6. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

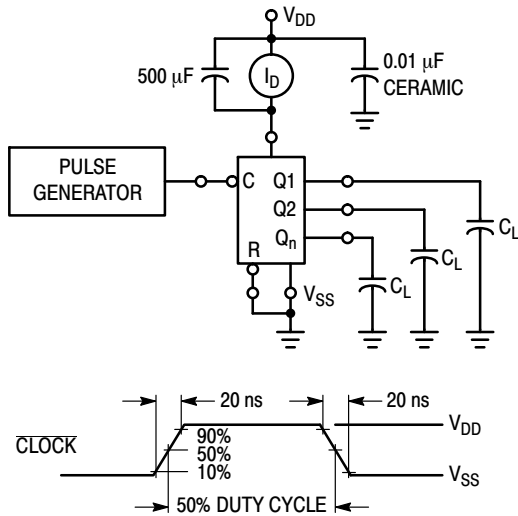


Figure 1. Power Dissipation Test Circuit and Waveform

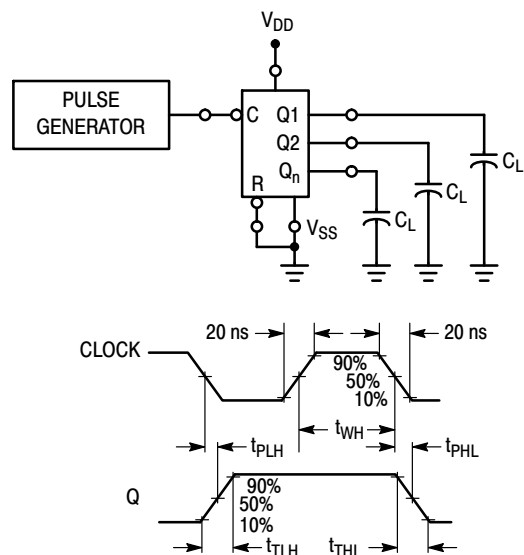


Figure 2. Switching Time Test Circuit and Waveforms

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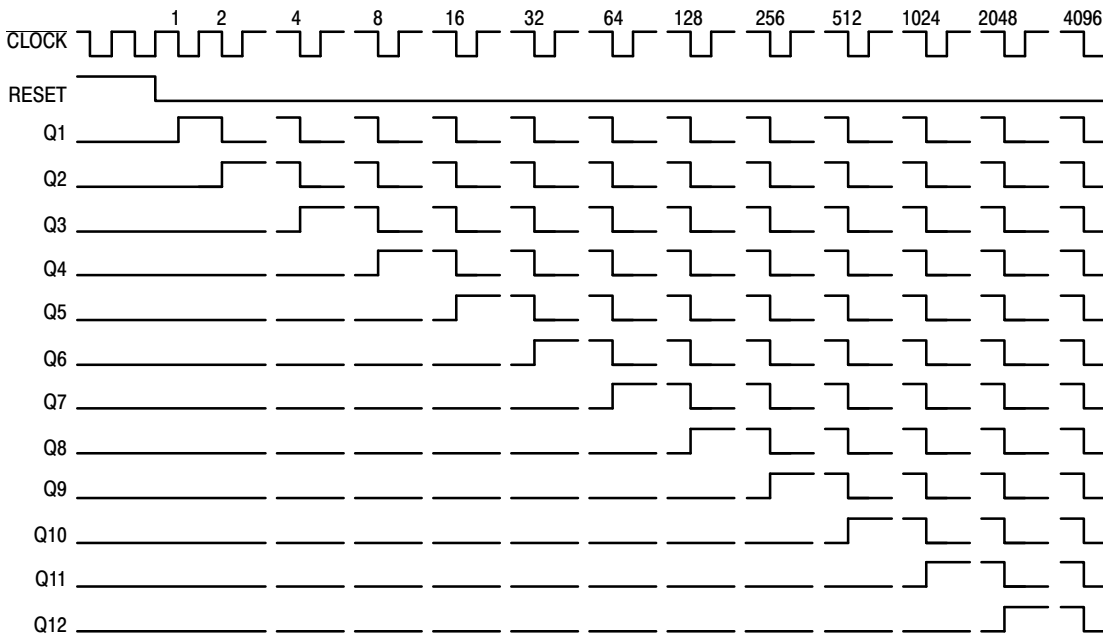


Figure 3. Timing Diagram

APPLICATIONS INFORMATION

TIME-BASE GENERATOR

A 60 Hz sinewave obtained through a 1.0 Megohm resistor connected directly to a standard 120 Vac power line is applied to the clock input of the MC14040B. By selecting

outputs Q5, Q10, Q11, and Q12 division by 3600 is accomplished. The MC14012B decodes the counter outputs, produces a single output pulse, and resets the binary counter. The resulting output frequency is 1.0 pulse/minute.

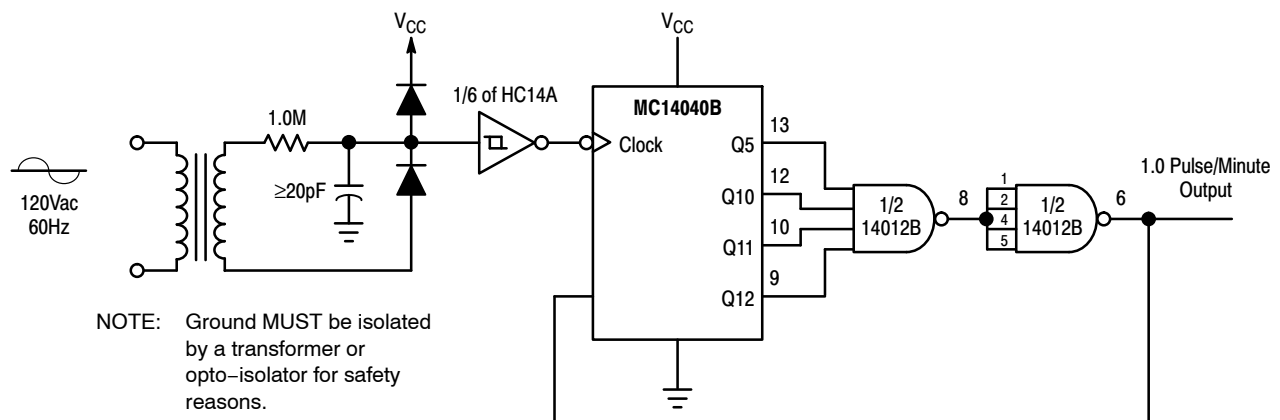


Figure 4. Time-Base Generator

MC14040B

PACKAGE DIMENSIONS

PDIP-16
P SUFFIX
PLASTIC DIP PACKAGE
CASE 648-08
ISSUE T



NOTES:

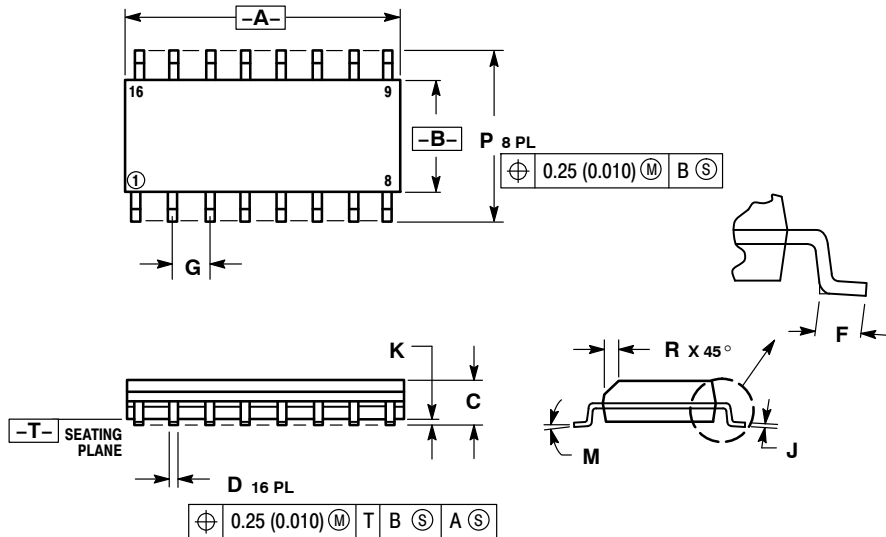
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

MC14040B

PACKAGE DIMENSIONS

SOIC-16
D SUFFIX
PLASTIC SOIC PACKAGE
CASE 751B-05
ISSUE K

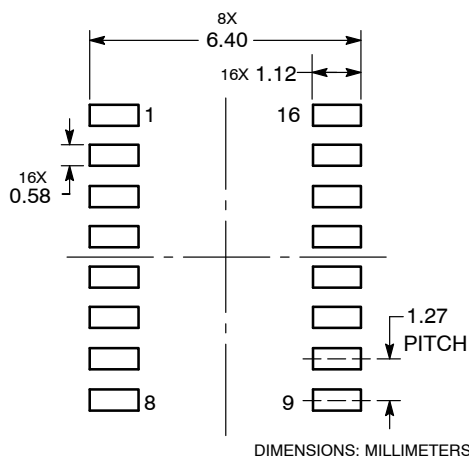


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0° - 7°		0° - 7°	
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

SOLDERING FOOTPRINT*



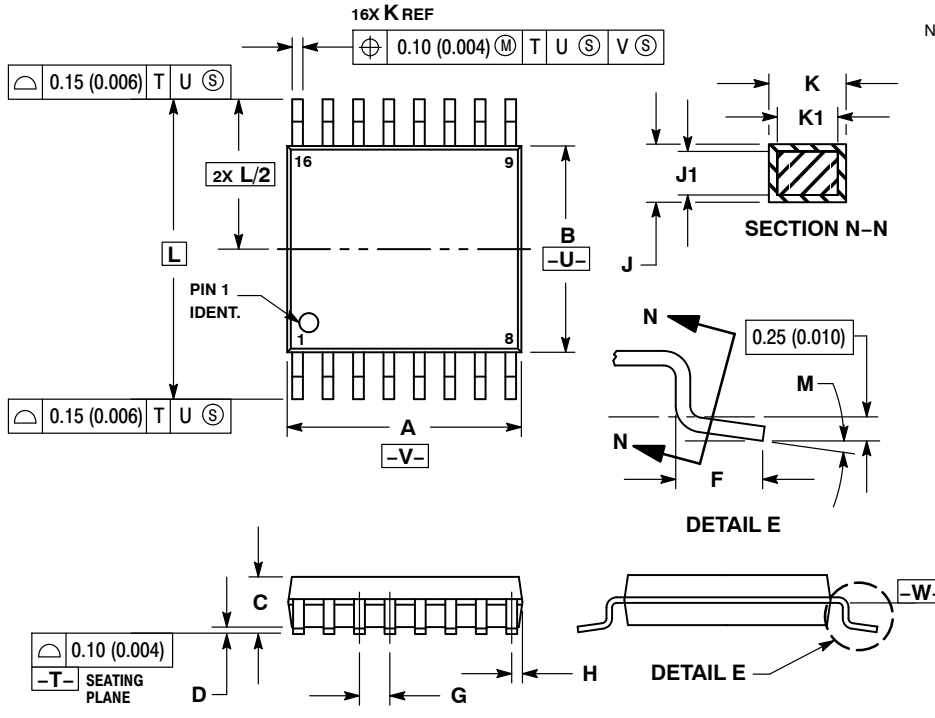
DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MC14040B

PACKAGE DIMENSIONS

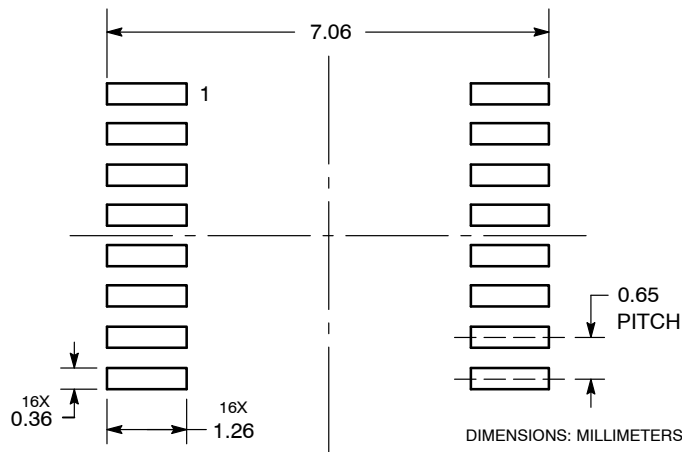
TSSOP-16
DT SUFFIX
PLASTIC TSSOP PACKAGE
CASE 948F-01
ISSUE B



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

SOLDERING FOOTPRINT*

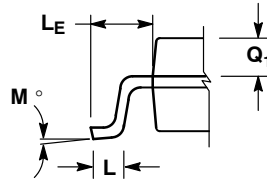
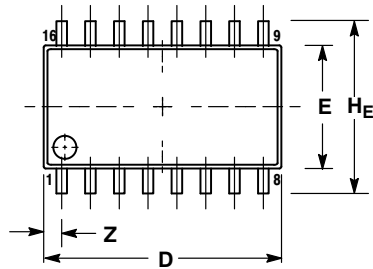


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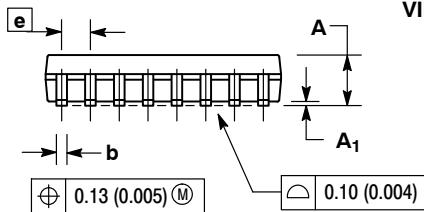
MC14040B

PACKAGE DIMENSIONS

SOEIAJ-16
F SUFFIX
PLASTIC EIAJ SOIC PACKAGE
CASE 966-01
ISSUE A



DETAIL P



VIEW P

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.10	0.20	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H _E	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L _E	1.10	1.50	0.043	0.059
M	0°	10°	0°	10°
Q ₁	0.70	0.90	0.028	0.035
Z	---	0.78	---	0.031

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